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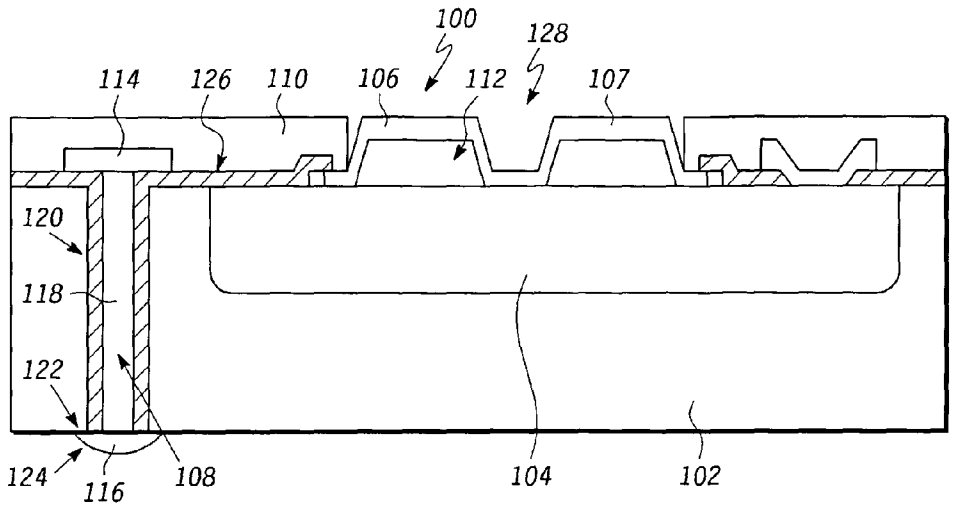
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(54) **Title:** METHODS AND APPARATUS HAVING WAFER LEVEL CHIP SCALE PACKAGE FOR SENSING ELEMENTS



(57) **Abstract:** Methods are provided for manufacturing a sensor (100). The method comprises depositing a sacrificial material (330) at a first predetermined thickness onto a wafer having at least one sense element mounted thereon, the sacrificial material deposited at least partially onto the at least one sense element, forming an encapsulating layer (332) at a second predetermined thickness less than the first predetermined thickness over the wafer and around the deposited sacrificial material, and removing the sacrificial material. Apparatus for a sensor manufactured by the aforementioned method are also provided.

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